21st IEEE International conference on Design, Test & Technology of Integrated Systems

November 4 - 6, 2026, Hammamet, Tunisia

IEEE DTTIS’2026 Call For Panels

Aim of the Panels:

A panel proposal should address a related hot topic that is of substantial interest to the majority of DTTIS attendees, because it is controversial or increasing in importance. The proposal should include a panel title, introduction, the name of the organizer, a proposed moderator, and proposed panelists, along with contact information for all. For more information, please contact the Panel Chair.

Papers are solicited in, but not limited to, the following topics:

Integrated Systems Design

- Analog, digital, mixed, and RF circuits design
- System-on-a-chip (SoC) & System of Chips (SoC), MPSoC, NoC, SIP, and NIP design
- Embedded/ multiprocessor systems
- Hardware design for AI
- AI accelerators
- MEMS, NEMS and MOEMS systems design
- Synthesis (physical, logic,...)
- Simulation, Validation & Verification
- Bio-engineering & Bio-chip design
- Electronics for energy harvesting
- Wireless communication systems design
- Opto-electronic System Design
- Biomedical Circuit & Systems
- Power electronics and systems design
- Sensory Systems Design
- Chiplet and disaggregation
- Intelligent and Autonomous Robotic Systems
- Embedded AI and TinyML
- Real-time inference under power, latency, and memory constraints
- Hardware–software co-design for intelligence at the edge
- Multi-agent coordination and distributed intelligence
- Heterogeneous computing platforms (CPU–GPU–FPGA–ASIC)
- Interoperability across hardware, software, and networks
- Hardware–software co-design for intelligence at the edge

Integrated Systems Testing

- Defect and Fault Modeling
- Analog, digital circuit test
- Mixed, and RF circuit testing
- MEMS/NEMS/MOEMS Testing
- 3D/2.5D Test
- Memory test
- Repair and diagnosis
- Reliability
- DFT, BIST and BISR
- Alternatives test strategies
- Fault Simulation, ATPG
- Yield Optimization
- Automotive reliability and test
- Reliability failures and modeling
- Electronic System Reliability
- Test and Security Issues
- ATE issues
- On-line Testing and fault Tolerance
- Delay testing

Integrated Systems Technology

- Process technologies
- Device modeling
- Material characterization
- Failure analysis
- Emerging technologies
- ICs Packaging
- Process technology
- Reliability issues
- 2.5 & 3D integration
- Circuit integrity

Special Issue

Analog Integrated Circuits and Signal Processing Journal

Panel Chair:

- Prof. Mourad Loulou, ENIS, Tunisia
  Mourad.loulou@enis.tn

Submission Deadline for Panels proposals: June, 30th 2026

Upon acceptance, the organizer(s) will take care of preparing and submitting a one-page abstract (to be included in the formal proceedings) covering the panel topic, coauthored by the organizer(s), the moderator and all panelists.

Paper online submission: https://dttis2026.si2e.tn/